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LAMINATED BOARD AND MULTILAYER PRINTED CIRCUIT BOARD**Publication Number:** 07-086710 (JP 7086710 A) , March 31, 1995**Inventors:**

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Applicants

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Application Number: 05-228445 (JP 93228445) , September 14, 1993**International Class (IPC Edition 6):**

- H05K-001/03
- B32B-017/04
- H05K-003/46

JAPIO Class:

- 42.1 (ELECTRONICS--- Electronic Components)
- 14.2 (ORGANIC CHEMISTRY--- High Polymer Molecular Compounds)

JAPIO Keywords:

- R124 (CHEMISTRY--- Epoxy Resins)

Abstract:

PURPOSE: To provide the title laminated board, multilayer printed circuit board, prepreg having small in-surface thermal expansion coefficient and low elastic coefficient.

CONSTITUTION: The title laminated board having insulating layer comprising resin parts 2 having sea-island structure and cloth reinforcement members 1 in thermal expansion coefficient of 3.0-10ppm/K in the in-surface direction of the insulating layer and the glass transition temperature of 150-300 deg.C in the insulating layer is obtained. Thus, the in-surface thermal expansion coefficient of laminated board, multilayer printed circuit board, prepreg, elastic coefficient are reduced thereby notably cutting down the thermal stress of mounting surface. Through these procedures, the reliability upon the connection to mounted element such as an LSI can be notably enhanced.

JAPIO

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